What is claimed is:

1. An embedding resin for embedding electronic parts,

wherein after a substrate in which a copper layer is formed on a cured product of the embedding resin is subjected to a pressure cooker test, the copper layer has a peeling strength of at least 588 N/m (0.6 kg/cm),

wherein the conditions of the pressure cooker test are 121°C, 100% by mass humidity, 2.1 atm and 168 hours, and the measurement method of the peeling strength is according to JIS C 5012, and the width of the copper layer is 10 mm.

2. An embedding resin for embedding electronic parts,

wherein after a substrate in which a copper layer is formed on a cured product of the embedding resin is subjected to a pressure cooker test, the copper layer has a peeling strength of at least 600 N/m (0.61 kg/cm),

wherein the conditions of the pressure cooker test are 121°C, 100% by mass humidity, 2.1 atm and 336 hours, and the measurement method of the peeling strength is according to JIS C 5012, and the width of the copper layer is 10 mm.

3. The embedding resin according to claim 1, which contains carbon black in an amount of not more than 0.5% by mass.

4. The embedding resin according to claim 1, which contains carbon black in an amount of not more than 0.4% by mass.

5. The embedding resin according to claim 1, which comprises a thermosetting resin and at least one inorganic filler.

6. The embedding resin according to claim 5, wherein the thermoplastic resin comprises at least one selected from a bisphenol epoxy resin, a naphthalene epoxy resin, a phenolnovolac epoxy resin, and a cresol novolac epoxy resin.

7. A wiring substrate comprising at least one electric part embedded in an embedding resin according to claim 1.

8. A wiring substrate comprising at least one electric part embedded in an embedding resin according to claim 1.

9. A wiring substrate comprising: a core substrate; and a build-up layer provided on at least one side of the core substrate and formed by alternately laminating an insulating layer and a wiring layer, wherein at least one of the core substrate and the build-up layer has an opening penetrating therethrough, and an electronic part is disposed in the opening and embedded with an embedding resin according to claim 1.

10. A wiring substrate comprising: a core substrate; and a build-up layer provided on at least one side of the core substrate and formed by alternately laminating an insulating layer and a wiring layer, wherein at least one of the core substrate and the build-up layer has an opening penetrating therethrough, and an electronic part is disposed in the opening and embedded with an embedding resin according to claim 1.